



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01330	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-01330		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/14/2017	12:05:11 PM	TEXAS INSTRUMENTS

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